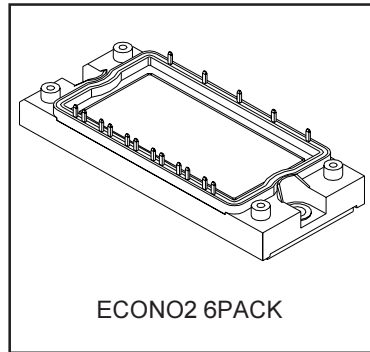


**IGBT SIXPACK MODULE**

**Features**

- Low V<sub>CE</sub> (on) Non Punch Through IGBT Technology
- Low Diode VF
- 10µs Short Circuit Capability
- Square RBSOA
- HEXFRED Antiparallel Diode with Ultrastop Reverse Recovery Characteristics
- Positive V<sub>CE</sub> (on) Temperature Coefficient
- Ceramic DBC Substrate
- Low Stray Inductance Design




V<sub>CES</sub> = 1200V

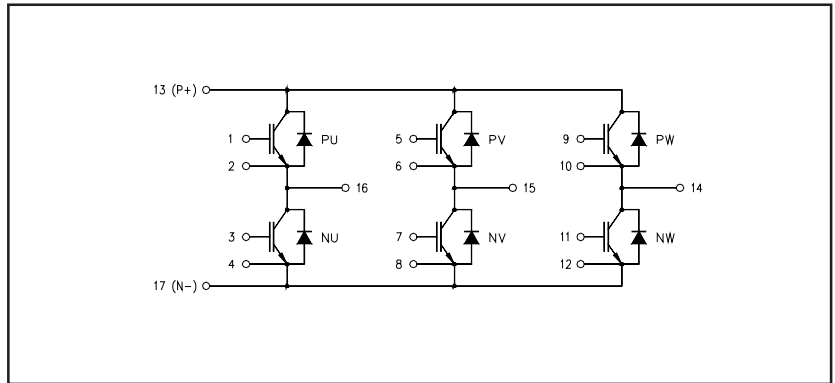
I<sub>C</sub> = 50A @ T<sub>C</sub>=80°C

t<sub>sc</sub> > 10µs @ T<sub>J</sub>=150°C

V<sub>CE(on)</sub> typ. = 2.45V

**Benefits**

- Benchmark Efficiency for Motor Control
- Rugged Transient Performance
- Low EMI, Requires Less Snubbing
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Low Junction to Case Thermal Resistance
- UL Approved E78996 



**Absolute Maximum Ratings**

	Parameter	Max.	Units
V <sub>CES</sub>	Collector-to-Emitter Voltage	1200	V
I <sub>C</sub> @ T <sub>C</sub> =25°C	Continuous Collector Current	75	A
I <sub>C</sub> @ T <sub>C</sub> =80°C	Continuous Collector Current	50	
I <sub>CM</sub>	Pulsed Collector Current (Ref. Fig. C.T.5)	150	
I <sub>LM</sub>	Clamped Inductive Load Current	150	
I <sub>F</sub> @ T <sub>C</sub> =25°C	Diode Continuous Forward Current	75	
I <sub>F</sub> @ T <sub>C</sub> =80°C	Diode Continuous Forward Current	50	
I <sub>FM</sub>	Pulsed Diode Maximum Forward Current	150	
V <sub>GE</sub>	Gate-to-Emitter Voltage	±20	V
P <sub>D</sub> @ T <sub>C</sub> =25°C	Maximum Power Dissipation (IGBT and Diode)	329	W
P <sub>D</sub> @ T <sub>C</sub> =80°C	Maximum Power Dissipation (IGBT and Diode)	184	
T <sub>J</sub>	Maximum Operating Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature Range	-40 to +125	
V <sub>ISOL</sub>	Isolation Voltage	AC 2500 (MIN)	V

**Thermal and Mechanical Characteristics**

	Parameter	Min	Typical	Maximum	Units
R <sub>θJC</sub> (IGBT)	Junction-to-Case IGBT	-	-	0.38	°C/W
R <sub>θJC</sub> (Diode)	Junction-to-Case Diode	-	-	0.70	
R <sub>θCS</sub> (Module)	Case-to-Sink, flat, greased surface	-	0.05	-	
	Mounting Torque (M5)	2.7	-	3.3	N*m
	Weight	-	170	-	g

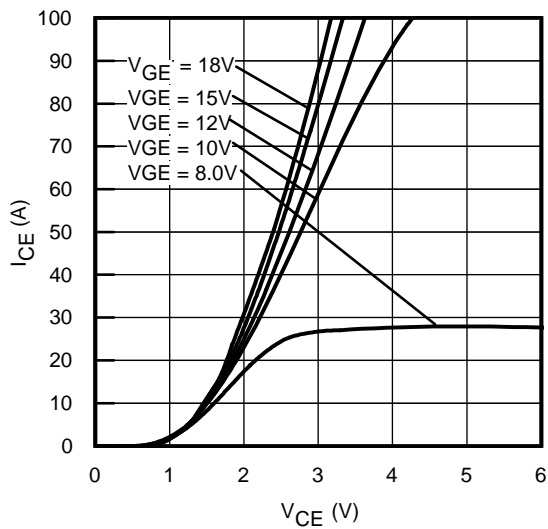
## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$BV_{(CES)}$	Collector-to-Emitter Breakdown Voltage	1200	-	-	V	$V_{GE} = 0$ $I_C = 500\mu\text{A}$
$\Delta V_{(BR)CES}/\Delta T_J$	Temp. Coefficient of Breakdown Voltage	-	0.31	-	V/ $^\circ\text{C}$	$V_{GE} = 0$ $I_C = 1\text{mA}$ ( $25^\circ\text{C} - 125^\circ\text{C}$ )
$V_{CE(ON)}$	Collector-to-Emitter Voltage	-	2.45	2.65	V	$I_C = 50\text{A}$ $V_{GE} = 15\text{V}$
		-	2.85	3.15		$I_C = 75\text{A}$ $V_{GE} = 15\text{V}$
		-	2.85	-		$I_C = 50\text{A}$ $V_{GE} = 15\text{V}$ $T_J = 125^\circ\text{C}$
		-	3.45	-		$I_C = 75\text{A}$ $V_{GE} = 15\text{V}$ $T_J = 125^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	4.0	4.9	6.0		$V_{CE} = V_{GE}$ $I_C = 250\mu\text{A}$
$\Delta V_{GE(th)}/\Delta T_J$	Threshold Voltage temp. coefficient	-	-12	-	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}$ $I_C = 1\text{mA}$ ( $25^\circ\text{C} - 125^\circ\text{C}$ )
$I_{CES}$	Zero Gate Voltage Collector Current	-	-	100	$\mu\text{A}$	$V_{GE} = 0$ $V_{CE} = 1200\text{V}$
		-	1000	-		$V_{GE} = 0$ $V_{CE} = 1200\text{V}$ $T_J = 125^\circ\text{C}$
$V_{FM}$	Diode Forward Voltage Drop	-	1.95	2.25	V	$I_F = 50\text{A}$
		-	2.20	2.60		$I_F = 75\text{A}$
		-	2.05	-		$I_F = 50\text{A}$ $T_J = 125^\circ\text{C}$
		-	2.40	-		$I_F = 75\text{A}$ $T_J = 125^\circ\text{C}$
$I_{GES}$	Gate-to-Emitter Leakage Current	-	-	$\pm 200$	nA	$V_{GE} = \pm 20\text{V}$

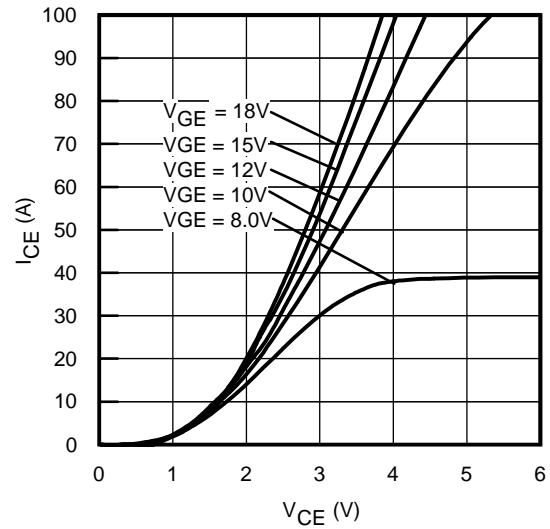
## Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$Q_G$	Total Gate Charge (turn-on)	-	355	535	nC	$I_C = 50\text{A}$
$Q_{GE}$	Gate-to-Emitter Charge (turn-on)	-	35	55		$V_{CC} = 600\text{V}$
$Q_{GC}$	Gate-to-Collector Charge (turn-on)	-	165	250		$V_{GE} = 15\text{V}$
$E_{ON}$	Turn-On Switching Loss	-	3600	4635	$\mu\text{J}$	$I_C = 50\text{A}$ $V_{CC} = 600\text{V}$
$E_{OFF}$	Turn-Off Switching Loss	-	3740	4780		$V_{GE} = 15\text{V}$ $R_G = 10\Omega$ $L = 400\mu\text{H}$
$E_{TOT}$	Total Switching Loss	-	7340	9415		$T_J = 25^\circ\text{C}$ ①
$E_{ON}$	Turn-On Switching Loss	-	5050	7100	$\mu\text{J}$	$I_C = 50\text{A}$ $V_{CC} = 600\text{V}$
$E_{OFF}$	Turn-Off Switching Loss	-	5525	7750		$V_{GE} = 15\text{V}$ $R_G = 10\Omega$ $L = 400\mu\text{H}$
$E_{TOT}$	Total Switching Loss	-	10575	14850		$T_J = 125^\circ\text{C}$ ①
$t_{d(on)}$	Turn-On delay time	-	60	80	ns	$I_C = 50\text{A}$ $V_{CC} = 600\text{V}$
$t_r$	Rise time	-	40	60		$V_{GE} = 15\text{V}$ $R_G = 10\Omega$ $L = 400\mu\text{H}$
$t_{d(off)}$	Turn-Off delay time	-	570	665		$T_J = 125^\circ\text{C}$
$t_f$	Fall time	-	205	270		
$C_{ies}$	Input Capacitance	-	4945	-	pF	$V_{GE} = 0$
$C_{oes}$	Output Capacitance	-	885	-		$V_{CC} = 30\text{V}$
$C_{res}$	Reverse Transfer Capacitance	-	100	-		$f = 1\text{Mhz}$
RBSOA	Reverse Bias Safe Operating Area	FULLSQUARE				$T_J = 150^\circ\text{C}$ $I_C = 150\text{A}$ $R_G = 10\Omega$ $V_{GE} = 15\text{V to } 0$
SCSOA	Short Circuit Safe Operating Area	10	-	-	$\mu\text{s}$	$T_J = 150^\circ\text{C}$ $V_{CC} = 900\text{V}$ $V_P = 1200\text{V}$ $R_G = 10\Omega$ $V_{GE} = 15\text{V to } 0$
$I_{rr}$	Diode Peak Rev. Recovery Current	-	87	-	A	$T_J = 125^\circ\text{C}$ $V_{CC} = 600\text{V}$ $I_F = 50\text{A}$ $L = 400\mu\text{H}$ $V_{GE} = 15\text{V}$ $R_G = 10\Omega$

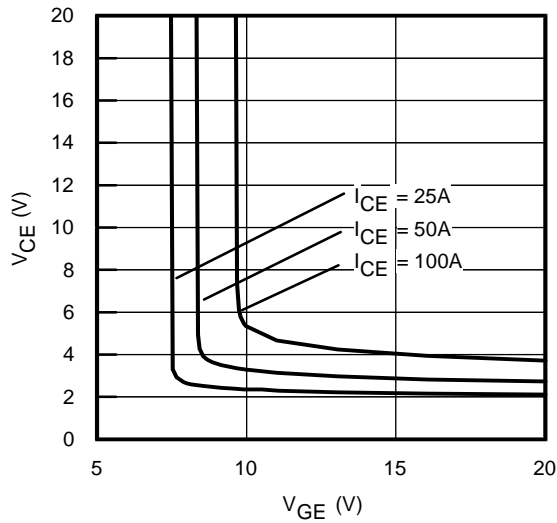
① Energy losses include "tail" and diode reverse recovery.



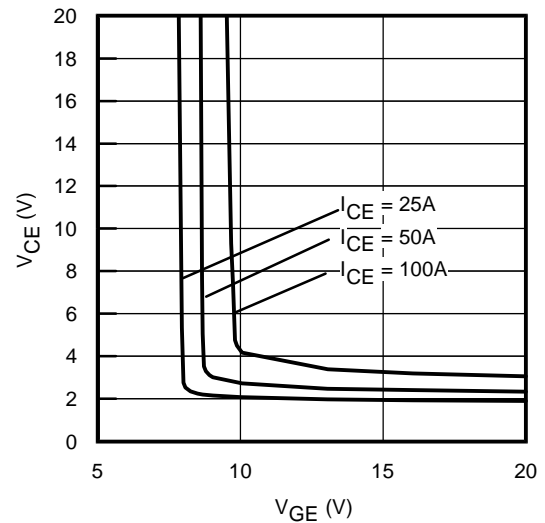
**Fig. 1** - Typ. IGBT Output Characteristics  
 $T_J = 25^\circ\text{C}$ ;  $t_p = 80\mu\text{s}$



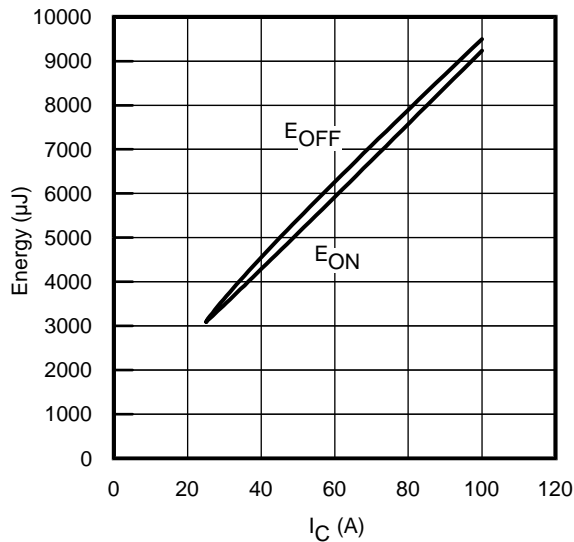
**Fig. 2** - Typ. IGBT Output Characteristics  
 $T_J = 125^\circ\text{C}$ ;  $t_p = 80\mu\text{s}$



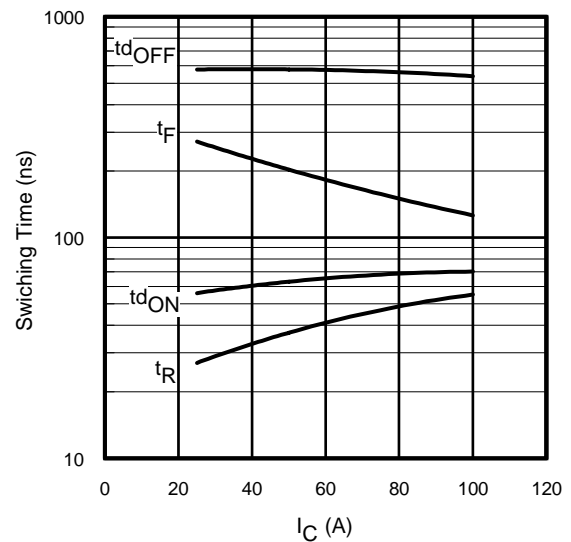
**Fig. 3** - Typical  $V_{CE}$  vs.  $V_{GE}$   
 $T_J = 25^\circ\text{C}$



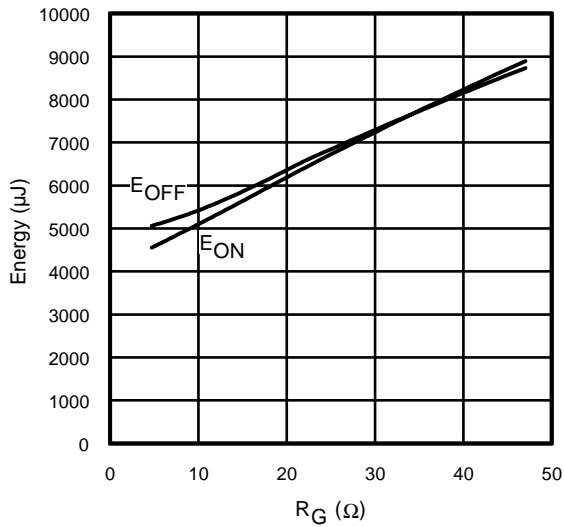
**Fig. 4** - Typical  $V_{CE}$  vs.  $V_{GE}$   
 $T_J = 125^\circ\text{C}$



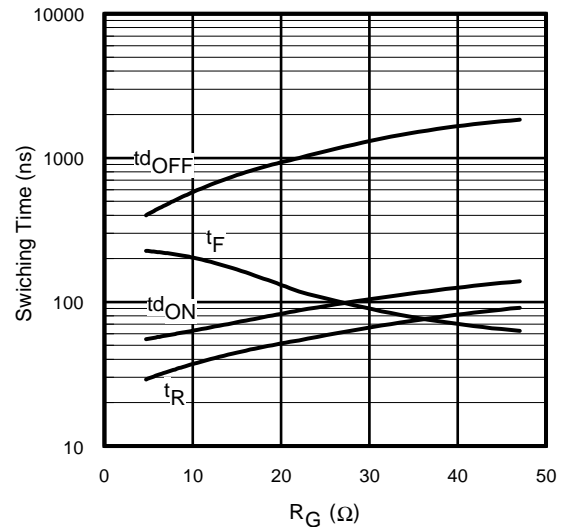
**Fig. 5** - Typ. Energy Loss vs.  $I_C$   
 $T_J = 125^\circ\text{C}$ ;  $L = 400\mu\text{H}$ ;  $V_{CE} = 600\text{V}$   
 $R_G = 10\Omega$ ;  $V_{GE} = 15\text{V}$



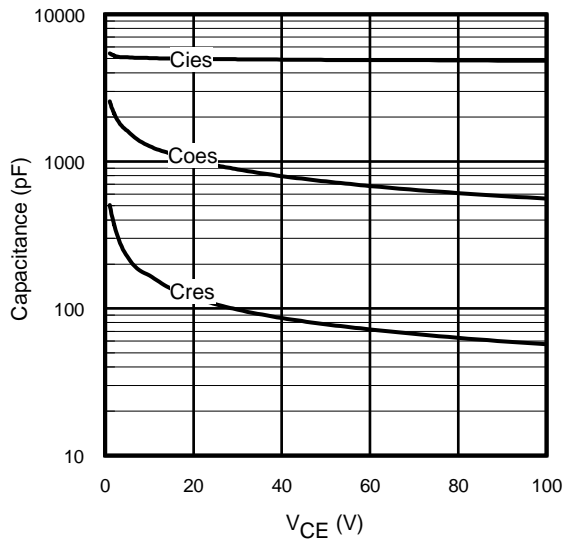
**Fig. 6** - Typ. Switching Time vs.  $I_C$   
 $T_J = 125^\circ\text{C}$ ;  $L = 400\mu\text{H}$ ;  $V_{CE} = 600\text{V}$   
 $R_G = 10\Omega$ ;  $V_{GE} = 15\text{V}$



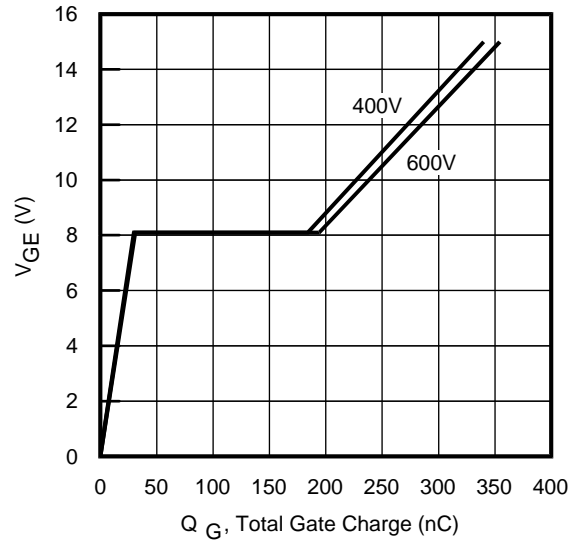
**Fig. 7** - Typ. Energy Loss vs.  $R_G$   
 $T_J = 125^\circ\text{C}$ ;  $L=400\mu\text{H}$ ;  $V_{CE}=600\text{V}$   
 $I_{CE}=50\text{A}$ ;  $V_{GE}=15\text{V}$



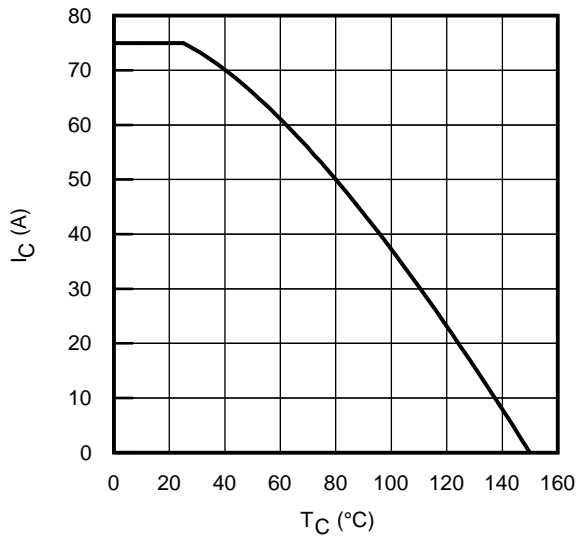
**Fig. 8** - Typ. Switching Time vs.  $R_G$   
 $T_J = 125^\circ\text{C}$ ;  $L=400\mu\text{H}$ ;  $V_{CE}=600\text{V}$   
 $I_{CE}=50\text{A}$ ;  $V_{GE}=15\text{V}$



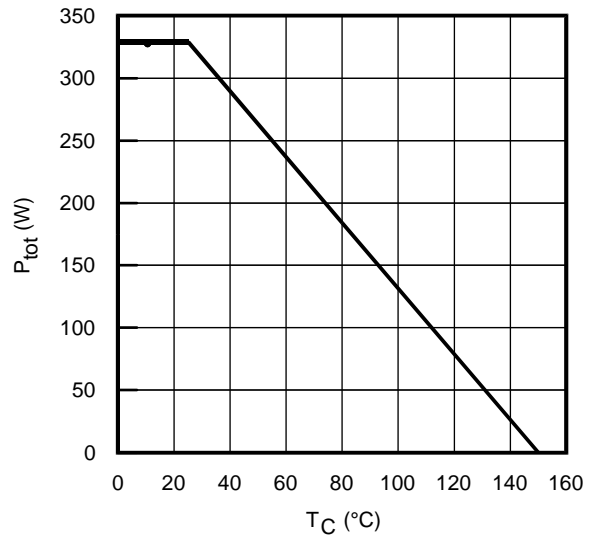
**Fig. 9** - Typ. Capacitance vs.  $V_{CE}$   
 $V_{GE}=0\text{V}$ ;  $f=1\text{MHz}$



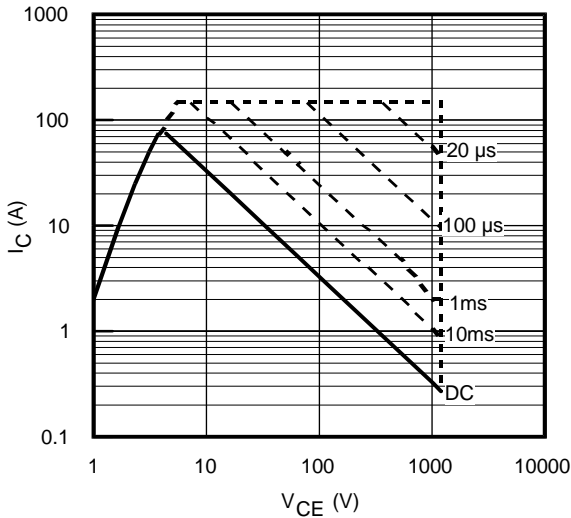
**Fig. 10** - Typical Gate Charge vs.  $V_{GE}$   
 $I_{CE}=50\text{A}$ ;  $L=600\mu\text{H}$



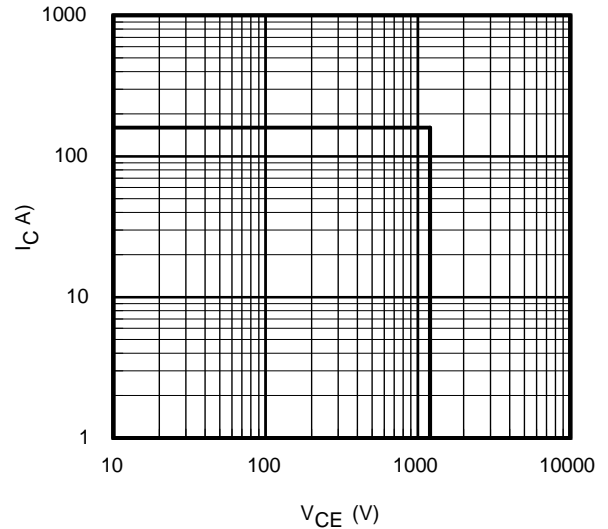
**Fig. 11** - Maximum DC Collector Current vs. Case Temperature



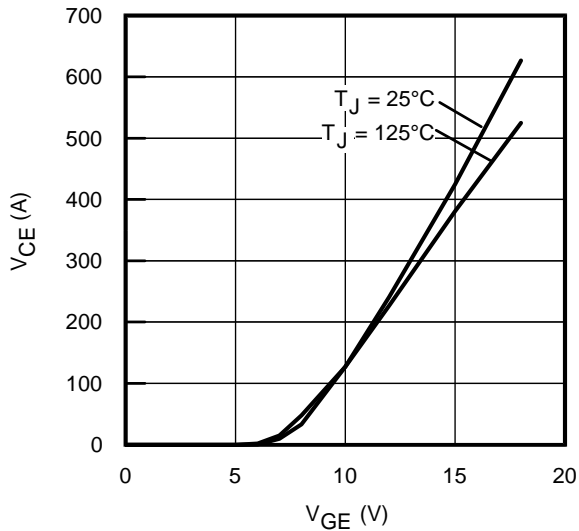
**Fig. 12** - Power Dissipation vs. Case Temperature



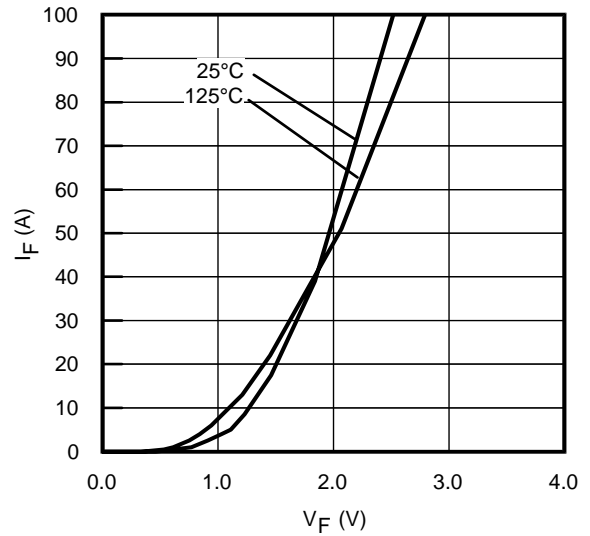
**Fig. 13 - Forward SOA**  
 $T_C = 25^\circ\text{C}; T_J \leq 150^\circ\text{C}$



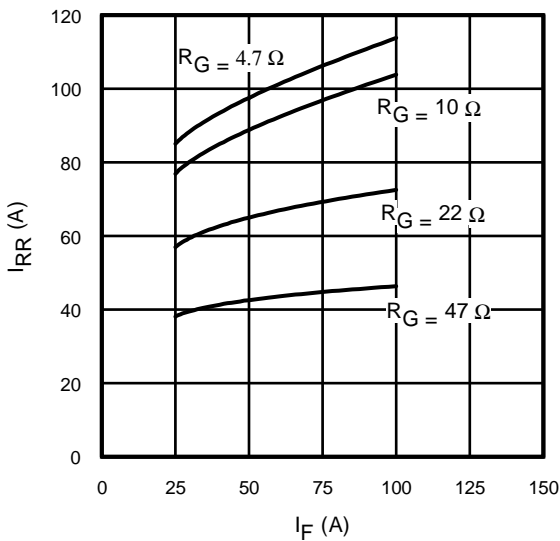
**Fig. 14 - Reverse Bias SOA**  
 $T_J = 150^\circ\text{C}; V_{GE} = 15\text{V}$



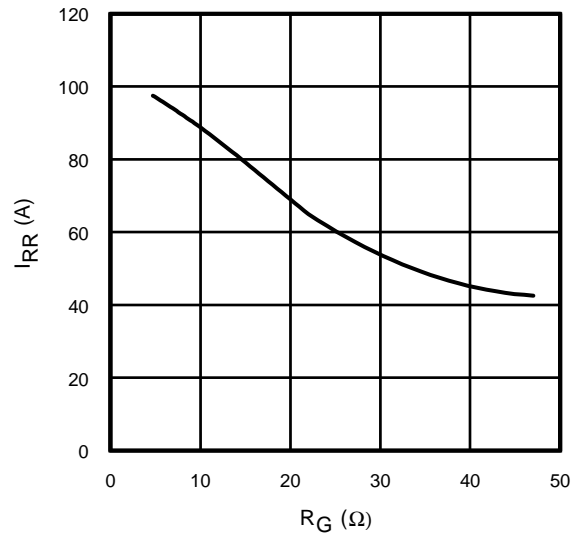
**Fig. 15 - Typ. Transfer Characteristics**  
 $V_{CE} = 50\text{V}; t_p = 10\mu\text{s}$



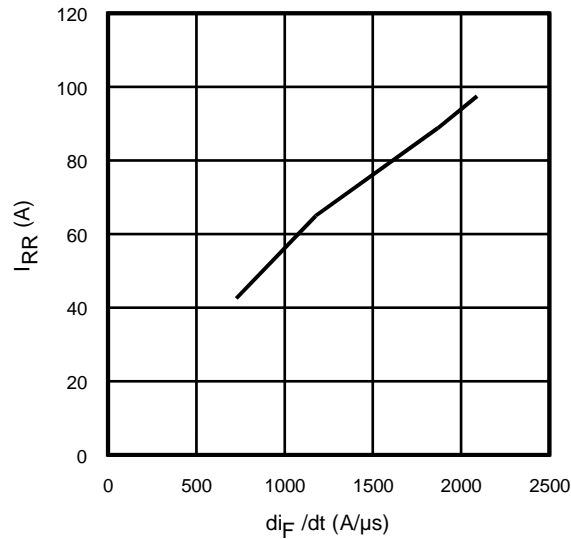
**Fig. 16 - Typ. Diode Forward Characteristics**  
 $t_p = 80\mu\text{s}$



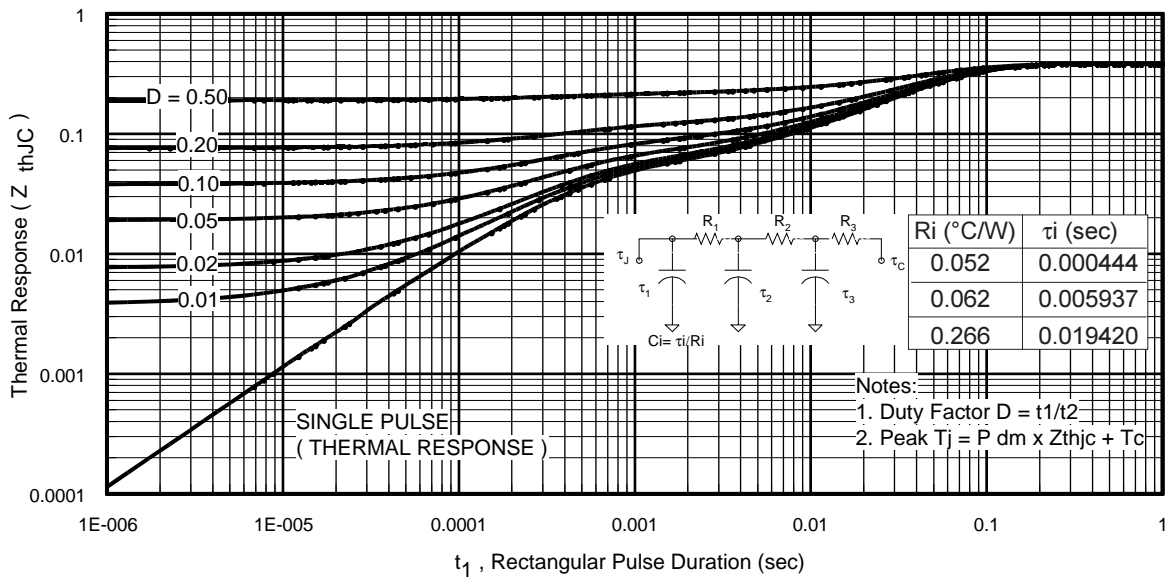
**Fig. 17 - Typical Diode  $I_{RR}$  vs.  $I_F$**   
 $T_J = 125^\circ\text{C}$



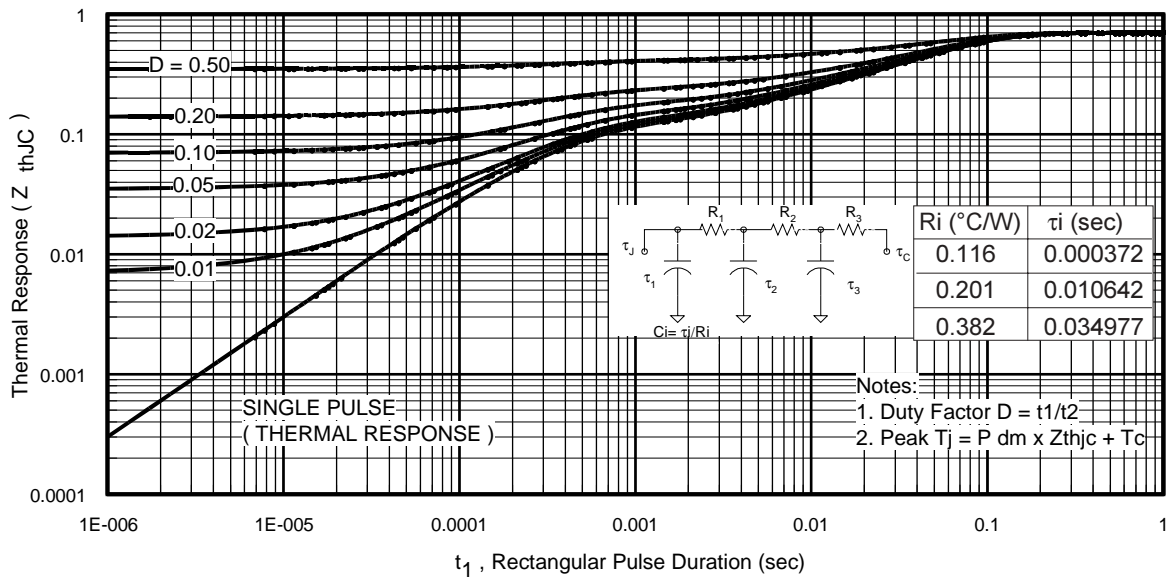
**Fig. 18 - Typical Diode  $I_{RR}$  vs.  $R_G$**   
 $T_J = 125^\circ\text{C}; I_F = 50\text{A}$



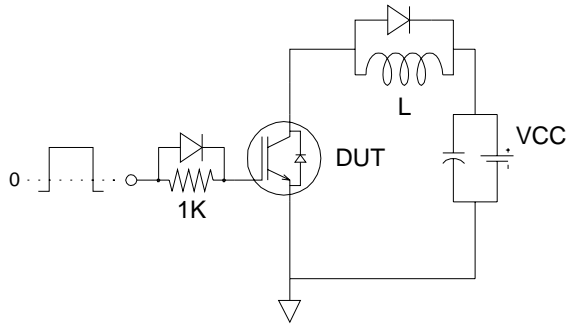
**Fig. 19-** Typical Diode  $I_{RR}$  vs.  $di_F/dt$ ;  $V_{CC}=600V$ ;  $V_{GE}=15V$ ;  $I_{CE}=50A$ ;  $T_J=125^{\circ}C$



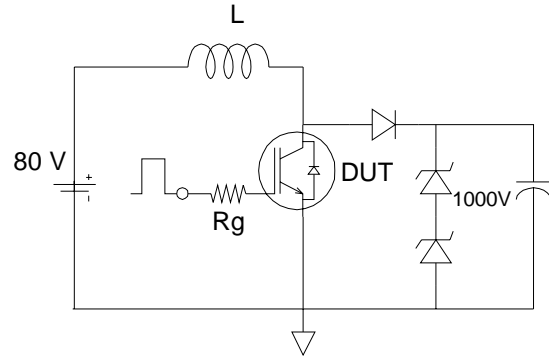
**Fig 20.** Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)



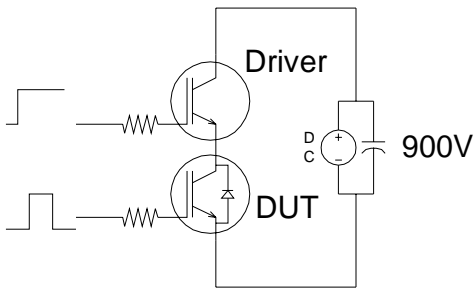
**Fig 21.** Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)



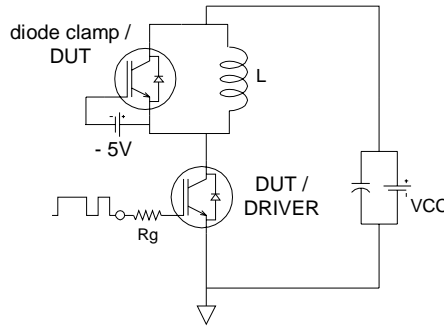
**Fig.C.T.1** - Gate Charge Circuit (turn-off)



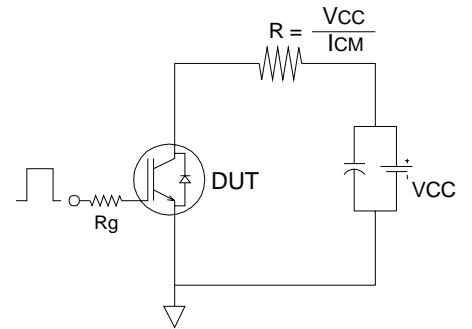
**Fig.C.T.2** - RBSOA Circuit



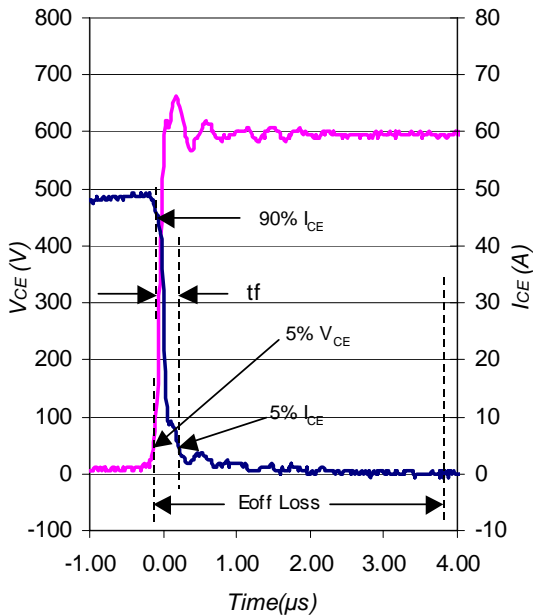
**Fig.C.T.3** - S.C. SOA Circuit



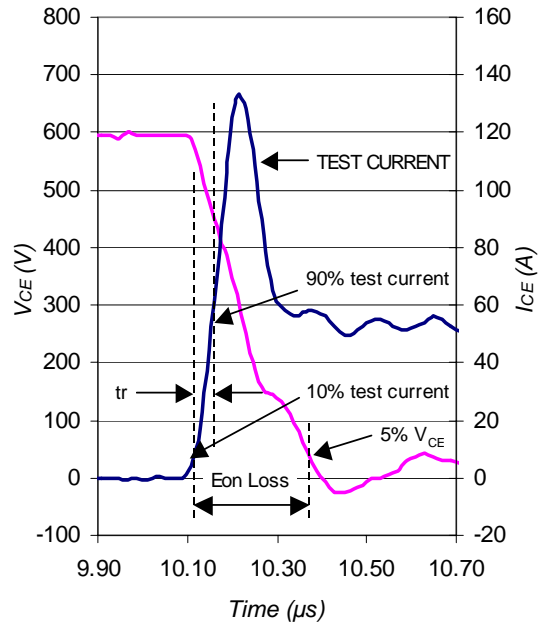
**Fig.C.T.4** - Switching Loss Circuit



**Fig.C.T.5** - Resistive Load Circuit



**Fig. WF1**-Typ. Turn-off Loss Waveform  
@  $T_J = 125^\circ\text{C}$  using Fig. CT.4



**Fig. WF2**-Typ. Turn-on Loss Waveform  
@  $T_J = 125^\circ\text{C}$  using Fig. CT.4

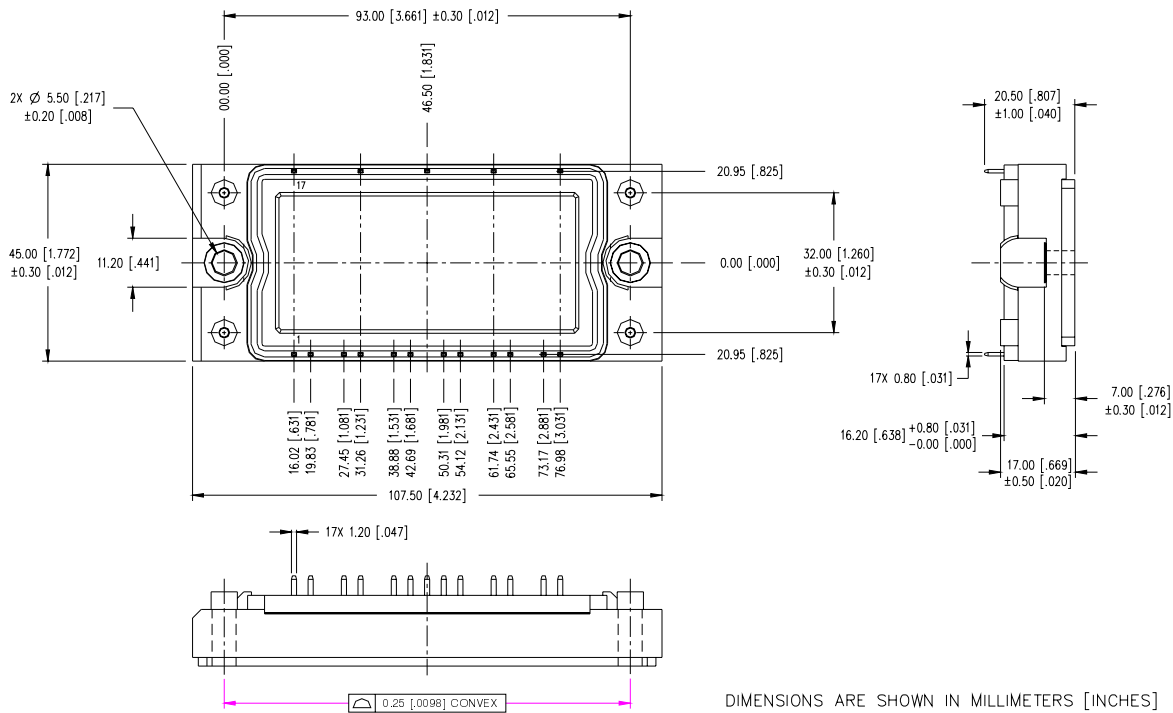
# GB50XF120K

Bulletin PD - 94567 rev.B 08/03

International  
**IR** Rectifier

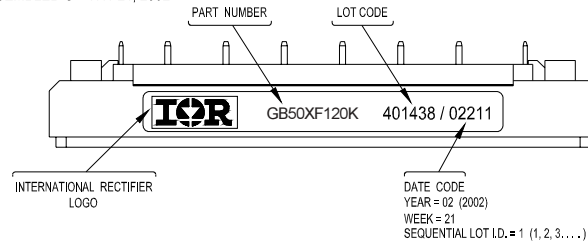
## Econo2 6Pak Package Outline

Dimensions are shown in millimeters (inches)



## Econo2 6Pak Part Marking Information

EXAMPLE: THIS IS A GB50XF120K  
LOT CODE: 401438  
ASSEMBLED ON WW 21, 2002



Data and specifications subject to change without notice.  
This product has been designed and qualified for Industrial market.  
Qualification Standards can be found on IR's Web site.

International  
**IR** Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
TAC Fax: (310) 252-7903

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